L Number	Hits	Search Text	DB	Time stamp
1	26	("6594542"|"6531399"|"6494765"|"6439964"|"2002052166"| ... "6404795"|"6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 07:55
2	2043	friction near3 (sensor sensors sensing senses (strain adj gauge))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 07:55
3	4	(("6594542"|"6531399"|"6494765"|"6439964"|"2002052166"| ...) and (friction near3 (sensor sensors sensing senses (strain adj gauge))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:00
4	2705284	wafer wafers substrate substrates semiconductor semiconductors	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:01
6	176	(friction near3 (sensor sensors sensing senses (strain adj gauge))) same (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:02
8	363	(friction near3 (sensor sensors sensing senses (strain adj gauge))) and (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:02
7	139	(friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:03
9	15464	(distance gap) adj (sensor sensors sensing sensed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:19
10	2	((friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer wafers substrate substrates semiconductor semiconductors)) and ((distance gap) adj (sensor sensors sensing sensed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:10
11	2336107	gap distance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:10
12	3	((("6594542"|"6531399"|"6494765"|"6439964"|"2002052166"| ...) and (friction near3 (sensor sensors sensing senses (strain adj gauge)))) and (gap distance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:12
13	719	(wafer wafers substrate substrates semiconductor semiconductors) same ((distance gap) adj (sensor sensors sensing sensed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:12
14	363909	abrasive abrade abrading abrades abrasives polish polishes polished polishing polisher polishers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:13
15	19	((wafer wafers substrate substrates semiconductor semiconductors) same ((distance gap) adj (sensor sensors sensing sensed))) same (abrasive abrade abrading abrades abrasives polish polishes polished polishing polisher polishers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:13

16	2	(((wafer wafers substrate substrates semiconductor semiconductors) same ((distance gap) adj (sensor sensors sensing sensed))) same (abrasive abrade abrading abrades abrasives polish polishes polished polishing polisher polishers)) and (friction near3 (sensor sensors sensing senses (strain adj gauge)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:15
21	106394	(distance gap) with (sensor sensors sensing sensed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:19
24	19	((friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer wafers substrate substrates semiconductor semiconductors)) and ((distance gap) with (sensor sensors sensing sensed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:33
25	4509	(wafer wafers substrate substrates semiconductor semiconductors) with ((distance gap) with (sensor sensors sensing sensed))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:25
26	92	((wafer wafers substrate substrates semiconductor semiconductors) with ((distance gap) with (sensor sensors sensing sensed))) and (strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:25
27	13	((wafer wafers substrate substrates semiconductor semiconductors) with ((distance gap) with (sensor sensors sensing sensed))) and (friction near3 (sensor sensors sensing senses (strain adj gauge)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:25
28	66948	dummy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:30
29	12163	dummy with (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:32
30	7	(dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (friction near3 (sensor sensors sensing senses (strain adj gauge)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:31
31	15002	dummy same (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:32
32	3	((friction near3 (sensor sensors sensing senses (strain adj gauge))) with (wafer wafers substrate substrates semiconductor semiconductors)) and (dummy same (wafer wafers substrate substrates semiconductor semiconductors))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:33
33	3255821	condition conditioner conditioning conditions conditioners	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:33
34	3555	(dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:34

35	497	(dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:34
36	32	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:35
37	96	((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:35
38	64	(((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) and (condition conditioner conditioning conditions conditioners)) and 451/$.ccls.) not (((dummy with (wafer wafers substrate substrates semiconductor semiconductors)) with (condition conditioner conditioning conditions conditioners)) and 451/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 08:38
39	1140	451/6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:29
41	235	((friction torque) same (distance gap) same (sensor sensors sensing senses sense)) and(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:31
42	32	((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:32
43	3	(((friction torque) same (distance gap) same (sensor sensors sensing senses sense))same(strain adj gauge)) and (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:38
44	2664	dummy adj (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:39
45	285	(condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:39
46	0	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) with arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:39
47	1	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) same arm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:39
49	0	(((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) and 451/$.ccls.) and wheels	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:40

48	26	((condition conditioner conditioning conditions conditioners) with (dummy adj (wafer wafers substrate substrates semiconductor semiconductors))) and 451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:41
50	155624	"L-shaped"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:42
51	803	"L-shaped" and 451/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:42
52	147	("L-shaped" and 451/$.ccls.) and (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 09:45
53	1109	451/56	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:11
54	0	"scott e. moore.".in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:11
55	10	(scott adj3 moore).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:11
56	267	scott with moore	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:12
57	248	scott near3 moore	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:12
58	1918	rachuba.xp.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:12
59	6	(scott near3 moore) and rachuba.xp.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 10:12
60	1		USPAT	2004/08/04 10:14
61	1		USPAT	2004/08/04 10:15
62	1		USPAT	2004/08/04 10:15
63	1		USPAT	2004/08/04 10:15
64	1		USPAT	2004/08/04 10:15
65	1		USPAT	2004/08/04 10:15
66	1		USPAT	2004/08/04 10:16
67	1		USPAT	2004/08/04 10:16
68	1		USPAT	2004/08/04 10:16
69	1		USPAT	2004/08/04 10:16
70	1		USPAT	2004/08/04 10:16
71	1		USPAT	2004/08/04 10:17
72	1		USPAT	2004/08/04 10:17
73	1		USPAT	2004/08/04 10:17
74	1		USPAT	2004/08/04 10:17
75	1		USPAT	2004/08/04 10:17